

Product Summary

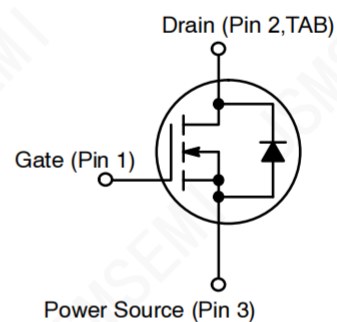
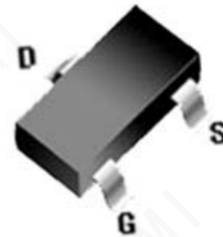
- V_{DS} 30V
- I_D 0.1A
- $R_{DS(ON)}$ (at $V_{GS}=10V$) $<8\Omega$
- 100% EAS Tested
- 100% ∇V_{DS} Tested

General Description

- Trench Power MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low $R_{DS(ON)}$
- Moisture Sensitivity Level 1
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free

Applications

- Power switching application
- Uninterruptible power supply
- DC-DC convertor
- Motor drivers



Absolute Maximum Ratings (TA=25°C unless otherwise noted)

Symbol	Parameter	Value	Unit
V_{DS}	Drain-Source voltage	30	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Continuous Drain Current	0.1	A
P_D	Power Dissipation	0.2	W
T_J	Junction Temperature	150	°C
T_{stg}	Storage Temperature	-55-150	°C
$R_{\theta JA}$	Thermal Resistance from Junction to Ambient	625	°C/W

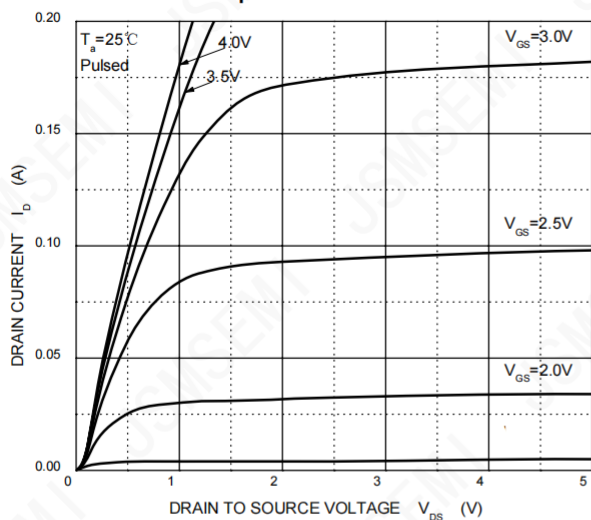
Electrical Characteristics(TA=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Off Characteristics						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 10μA	30			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V,V _{GS} = 0V			0.2	μA
Gate –Source leakage current	I _{GSS}	V _{GS} =±20V, V _{DS} = 0V			±2	μA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = 3V, I _D =100μA	0.8		1.5	V
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = 4V, I _D =10mA			8	Ω
		V _{GS} =2.5V,I _D =1mA			13	Ω
Forward Transconductance	g _{FS}	V _{DS} =3V, I _D = 10mA	20			mS
Dynamic Characteristics*						
Input Capacitance	C _{iss}	V _{DS} =5V,V _{GS} =0V,f =1MHz		13		pF
Output Capacitance	C _{oss}			9		pF
Reverse Transfer Capacitance	C _{rss}			4		pF
Switching Characteristics*						
Turn-On Delay Time	t _{d(on)}	V _{GS} =5V, V _{DD} =5V, I _D =10mA, R _g =10Ω, R _L =500Ω		15		ns
Rise Time	t _r			35		ns
Turn-Off Delay Time	t _{d(off)}			80		ns
Fall Time	t _f			80		ns

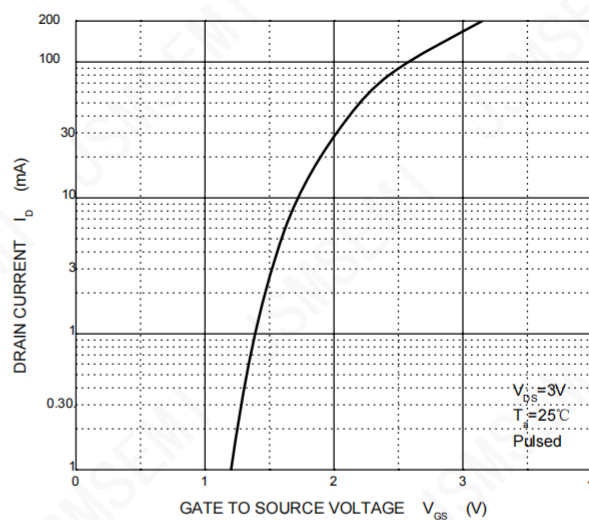
*These parameters have no way to verify.

Typical Performance Characteristics

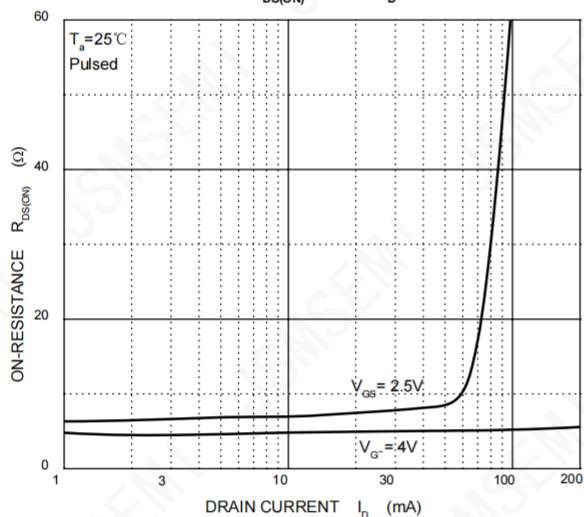
Output Characteristics



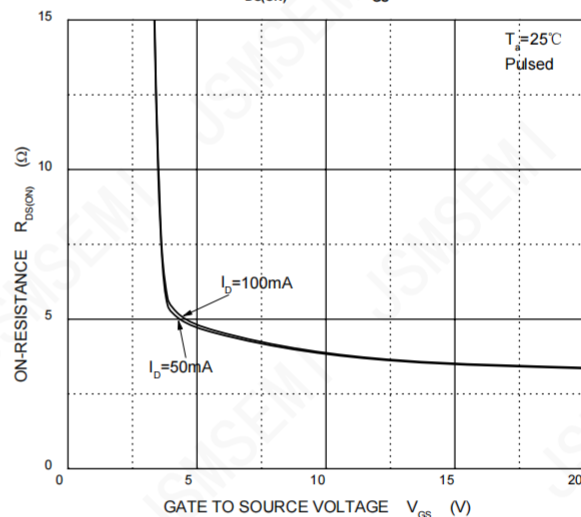
Transfer Characteristics



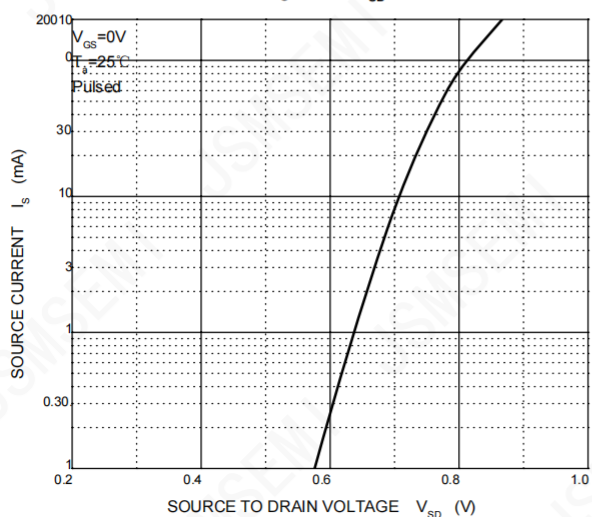
$R_{DS(ON)}$ — I_D



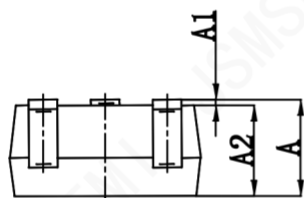
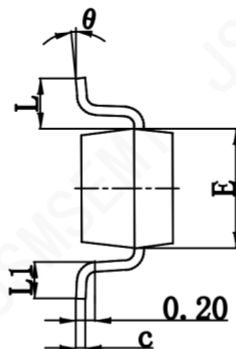
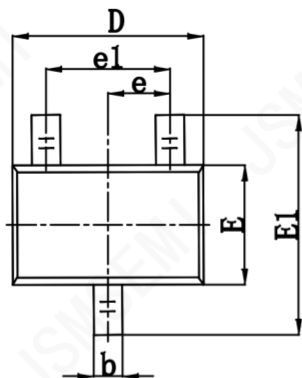
$R_{DS(ON)}$ — V_{GS}



I_S — V_{SD}

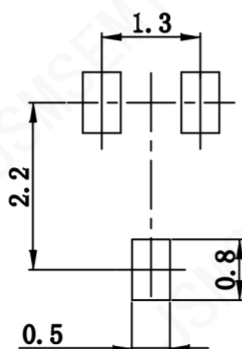


SOT-323 package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.200	0.400	0.008	0.016
c	0.080	0.150	0.003	0.006
D	2.000	2.200	0.079	0.087
E	1.150	1.350	0.045	0.053
E1	2.150	2.450	0.085	0.096
e	0.650 TYP		0.026 TYP	
e1	1.200	1.400	0.047	0.055
L	0.525 REF		0.021 REF	
L1	0.260	0.460	0.010	0.018
θ	0°	8°	0°	8°

SOT-323 Suggested pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05\text{mm}$.
3. The pad layout is for reference purposes only.

Revision History

Rev.	Change	Date
V1.0	Initial version	6/27/2021

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